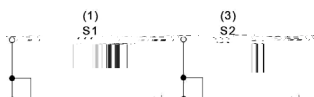
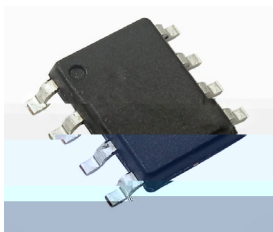


SOP-8 P MOS Dual P-Channel MOSFET in a SOP-8 Plastic Package.

Super high dense cell design for low $R_{DS(ON)}$, Rugged and reliable. HF Product.

Power Management in Notebook computer, Portable Equipment and Battery powered systems.



PIN1 S1 PIN 2 G1 PIN 3 S2 PIN 4 G2(A)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	±12	V
Continuous Drain Current	I_D^*	-3.0	A
Pulsed Drain Current	I_{DM}^*	-12	A
Diode Continuous Forward Current	I_S^*	-2.0	A
Power Dissipation for Single Operation	$P_D^* (T_a=25^\circ C)$	2	W
Power Dissipation for Single Operation	$P_D^* (T_a=100^\circ C)$	0.8	W
Maximum Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 ~ 150	
Thermal Resistance-Junction to Ambient	R_{JA}^*	62.5	/W

Note:

* Surface Mounted on 1in2 pad area, t = 10sec.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_{DS}=-250\text{ A}$	-20			V

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Gate Resistance	R_G^b	$V_{GS}=0V$ $V_{DS}=0V$ $F=1MHz$		6		Ω
Input Capacitance	C_{iss}^b	$V_{GS}=0V$ $V_{DS}=-6V$ Frequency=1.0MHz		415		pF
Output Capacitance	C_{oss}^b			223		
Reverse Transfer Capacitance	C_{rss}^b			84		
Turn-on Delay Time	$t_{d(ON)}^b$	$V_{DD}=-6V$ $R_L=6$ $I_{DS}=-1A$ $V_{GEN}=-10V$ $R_G=6$		13	25	ns
Turn-on Rise Time	T_r^b			36	60	
Turn-off Delay Time	$T_{d(OFF)}^b$			42	70	
Turn-off Fall Time	T_f^b			34	60	

Notes:

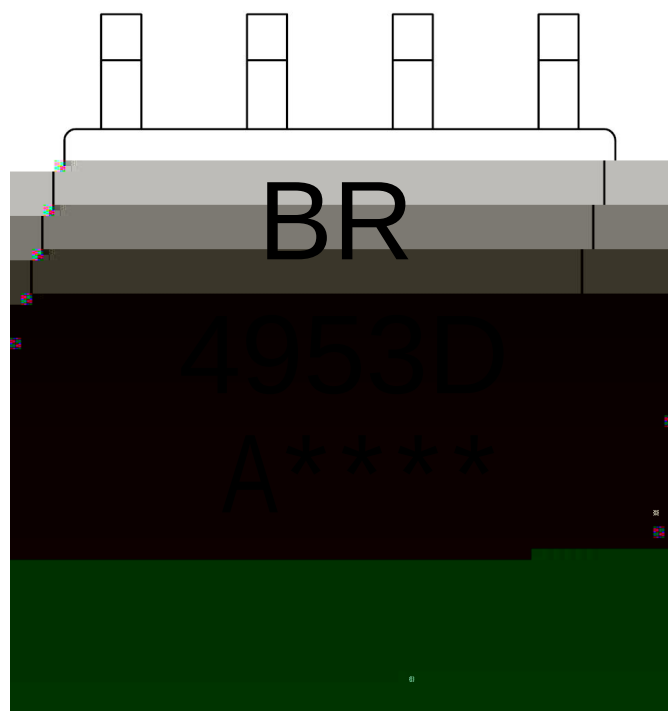
a : Pulse test ; pulse width 300 s, duty cycle 2%.

b : Guaranteed by design, not subject to production testing.

/ Package Dimensions



/ Marking Instructions



BR

4953D

A: , A B C D.....

Note:

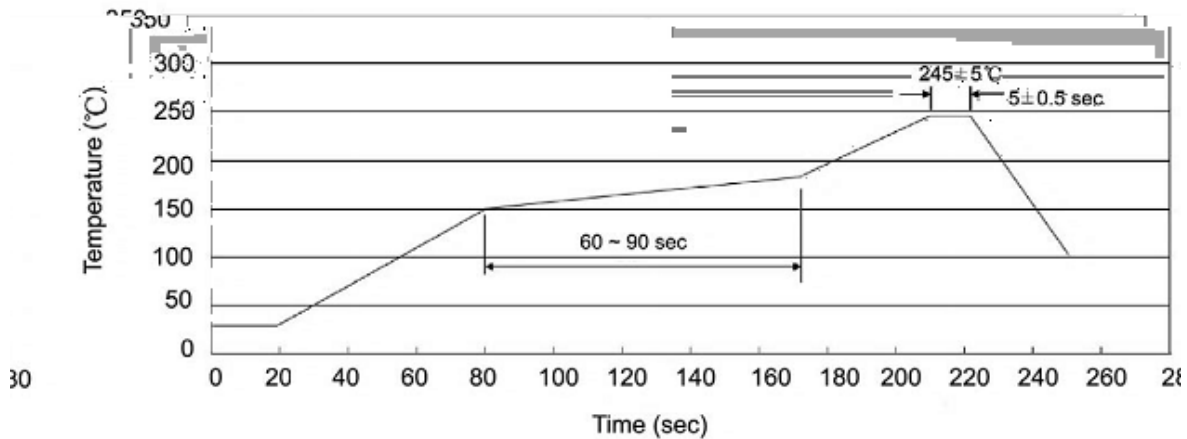
BR: Company Code.

4953D: Product Type

A: Chip sign(Flag bit may be empty,or the letter A B C D.....).

****: Lot No. Code, code change with Lot No.

() / Whp shrdwxrh Prr iioh irr IU Uhi orw Vroghriqj +Pe-Frhh,



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type Units